

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
20V	6.3mΩ@4.5V	50A

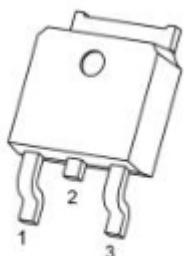
Feature

- $V_{DS} = 20V, I_D = 50A$
- $R_{DS(ON)} < 8m\Omega$ @ $V_{GS}=4.5V$
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation

Applications

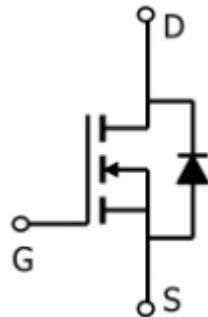
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

Package

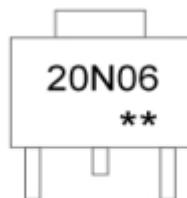


TO-252(G:1 D:2 S:3)

Circuit diagram



Marking



20N06 : Product code
 ** : Week code.

Absolute maximum ratings

($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current, $V_{GS} @ 4.5V^3$	$I_D @ T_A = 25^\circ\text{C}$	50	A
Drain Current, $V_{GS} @ 4.5V^3$	$I_D @ T_A = 70^\circ\text{C}$	38	A
Pulsed Drain Current ¹	I_{DM}	120	A
Total Power Dissipation	$P_D @ T_A = 25^\circ\text{C}$	3.13	W
Maximum Thermal Resistance, Junction-case	R_{thj-c}	5	$^\circ\text{C}/\text{W}$
Maximum Thermal Resistance, Junction-ambient ³	R_{thj-a}	40	$^\circ\text{C}/\text{W}$
Storage Temperature Range	T_{STG}	-55 to 150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to 150	$^\circ\text{C}$

Electrical characteristics

($T_A=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	20			V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 4.5\text{V}, I_{\text{D}} = 20\text{A}$		6.3	8	$\text{m}\Omega$
		$V_{\text{GS}} = 2.5\text{V}, I_{\text{D}} = 12\text{A}$		8	13	
Gate threshold voltage ²	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250\mu\text{A}$	0.5	0.7	1.2	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}} = 16\text{V}, V_{\text{GS}} = 0\text{V}$			10	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 12\text{V}, V_{\text{DS}} = 0\text{V}$			± 100	μA
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 5\text{V}, I_{\text{D}} = 20\text{A}$		130		S
Switching Characteristics						
Total Gate Charge(4.5V)	Q_g	$I_{\text{D}} = 20\text{A}, V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 4.5\text{V}$		62	99.2	nC
Gate-Source Charge	Q_{gs}			4		
Gate-Drain Charge	Q_{gd}			21		
Turn-On Delay Time	$T_{\text{d}(\text{on})}$	$V_{\text{DS}} = 10\text{V}, I_{\text{D}} = 1\text{A}, R_G = 3.3\Omega, V_{\text{GS}} = 5\text{V}$		12		nS
Rise Time	T_r			20		
Turn-Off Delay Time	$T_{\text{d}(\text{off})}$			100		
Fall Time	T_f			80		
Dynamic characteristics						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 10\text{V}, f = 1\text{MHz}$		4000	6400	pF
Output Capacitance	C_{oss}			780		
Reverse Transfer Capacitance	C_{rss}			625		
Drain-Source Diode Characteristics						
Forward On Voltage2	V_{SD}	$I_s = 10\text{A}, V_{\text{GS}} = 0\text{V}$			1.2	V
Reverse Recovery Time	t_{rr}	$I_s = 20\text{A}, V_{\text{GS}} = 0\text{V}, di/dt = 100\text{A}/\mu\text{s}$		43		nS
Reverse Recovery Charge	Q_{rr}			26		nC

Notes:

1. Pulse width limited by Max. Junction temperature.
2. Pulse test
3. Surface mounted on 1 in² 2oz copper pad of FR4 board, t <10sec; 135 °C/W when mounted on min. copper pad.
4. Maximum current limited by package.

Typical Characteristics

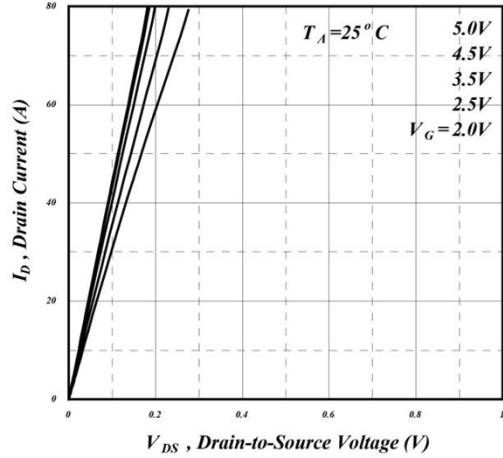


Fig 1. Typical Output Characteristics

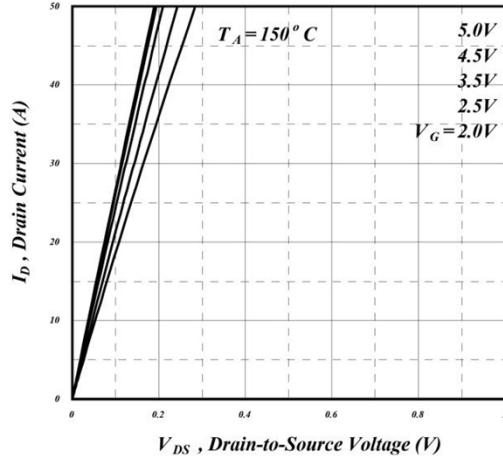


Fig 2. Typical Output Characteristics

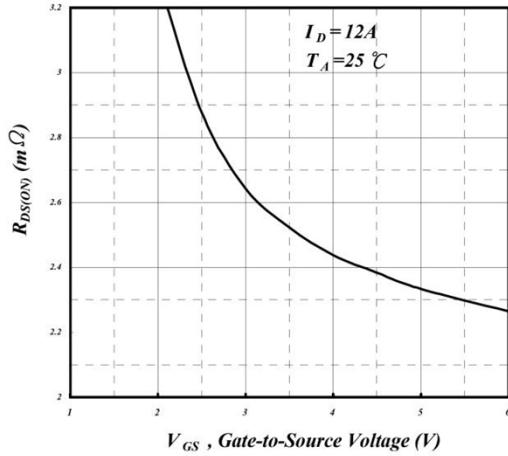


Fig 3. On-Resistance v.s. Gate Voltage

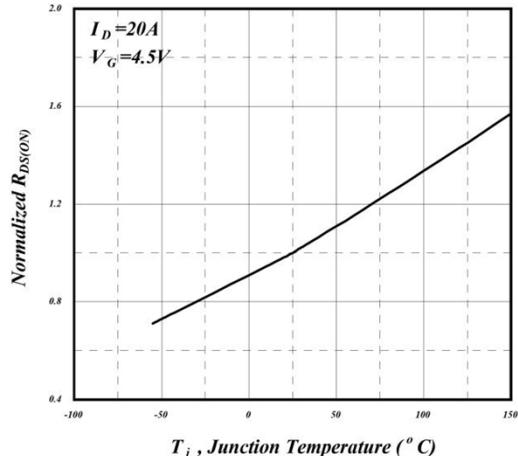


Fig 4. Normalized On-Resistance v.s. Junction Temperature

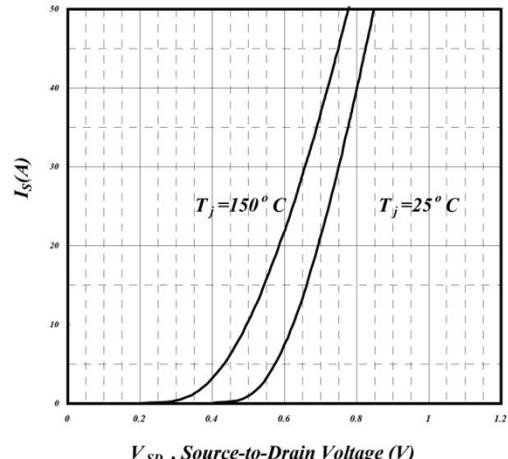


Fig 5. Forward Characteristic of Reverse Diode

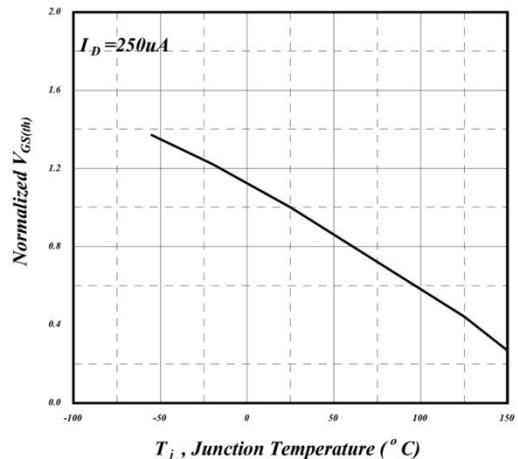


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

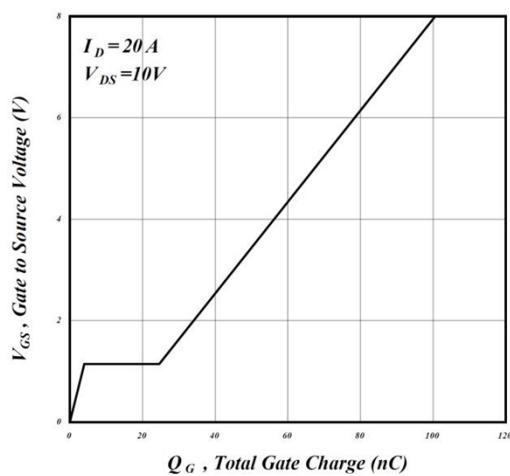


Fig 7. Gate Charge Characteristics

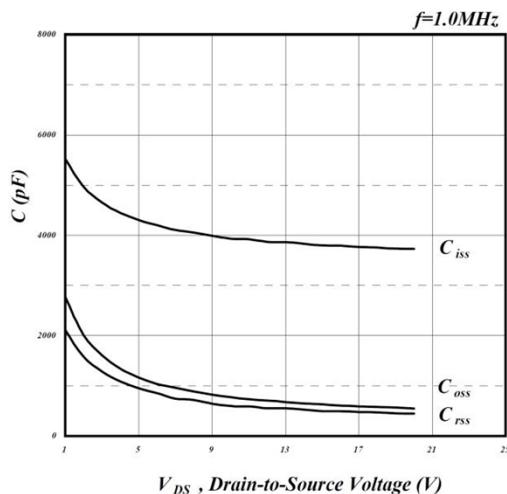


Fig 8. Typical Capacitance Characteristics

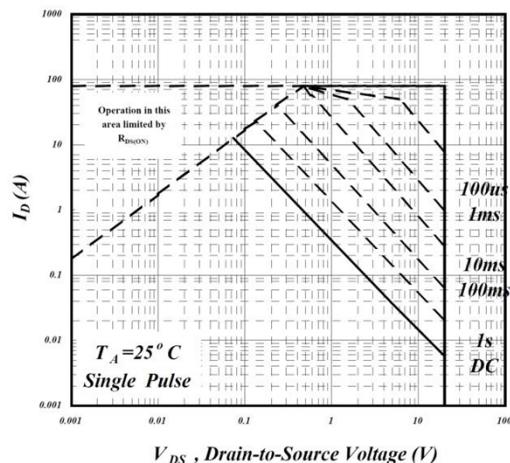


Fig 9. Maximum Safe Operating Area

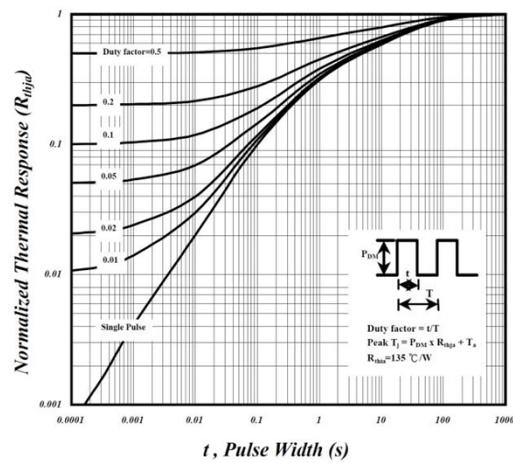


Fig 10. Effective Transient Thermal Impedance

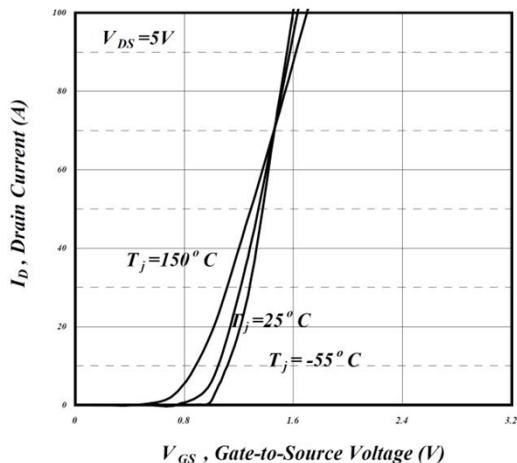


Fig 11. Transfer Characteristics

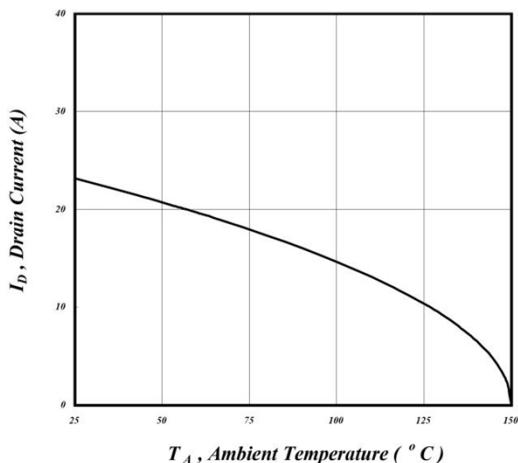
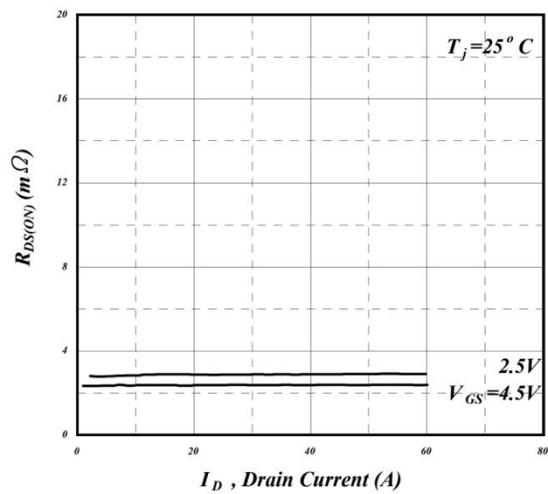


Fig 12. Drain Current v.s. Ambient Temperature



**Fig 13. Typ. Drain-Source on State
Resistance**

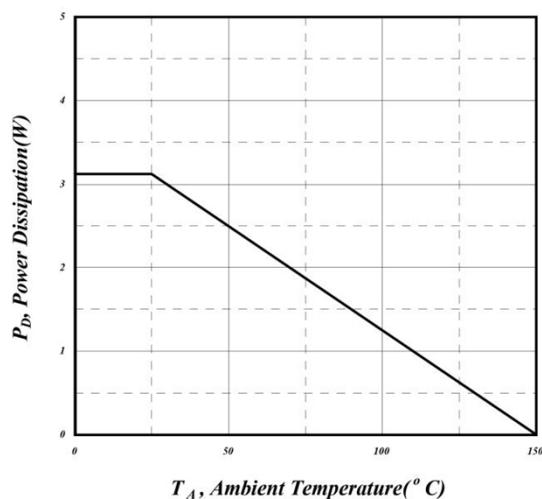
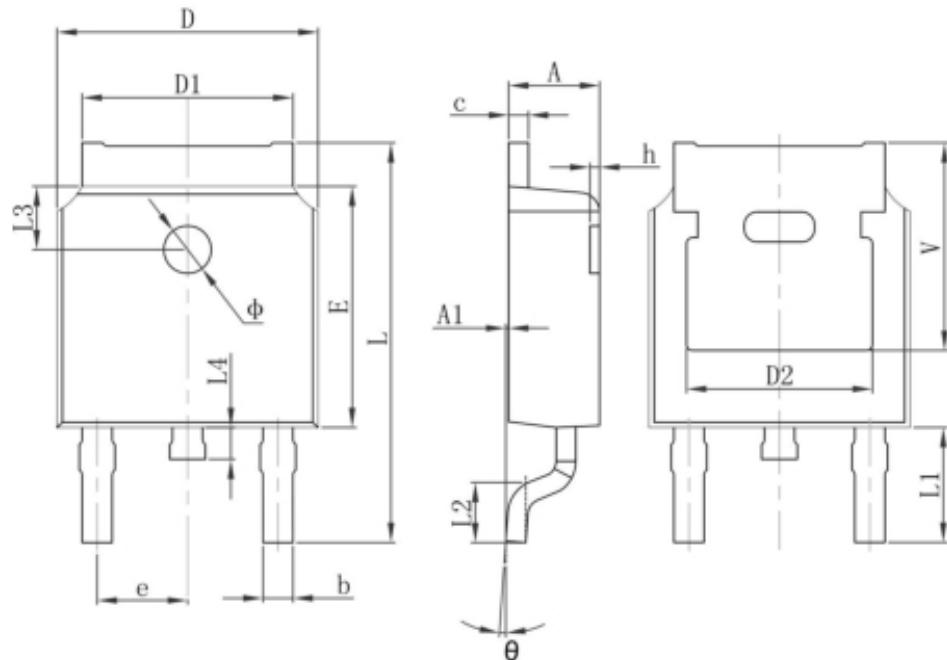


Fig 14. Total Power Dissipation

TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	